

ON Semiconductor®

FQA6N90C-F109

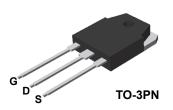
N-Channel QFET $^{\circledR}$ MOSFET 900 V, 6 A, 2.3 Ω

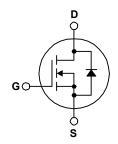
Features

- 6 A, 900 V, $R_{DS(on)}$ = 2.3 Ω (Max.) @ V_{GS} = 10 V, I_D = 3 A
- Low Gate Charge (Typ. 30 nC)
- Low Crss (Typ. 11 pF)
- 100% Avalanche Tested
- · RoHS Compliant

Description

This N-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	FQA6N90C-F109	Unit	
V _{DSS}	Drain-Source Voltage	900	V	
I _D	Drain Current - Continuous (T _C = 25°C)	6.0	А	
	- Continuous (T _C = 100°C)	3.87	А	
I _{DM}	Drain Current - Pulsed (Note	1) 24.0	Α	
V _{GSS}	Gate-Source Voltage	± 30	V	
E _{AS}	Single Pulsed Avalanche Energy (Note	2) 650	mJ	
I _{AR}	Avalanche Current (Note	1) 6.0	А	
E _{AR}	Repetitive Avalanche Energy (Note	1) 19.8	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note	3) 4.0	V/ns	
P _D	Power Dissipation (T _C = 25°C)	198	W	
	- Derate above 25°C	1.59	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C	
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C	

Thermal Characteristics

Symbol	Parameter	FQA6N90C-F109	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.63	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA6N90C-F109	FQA6N90C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	900			V
$\Delta BV_{DSS}/$ ΔT_J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		1.07		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 900 V, V _{GS} = 0 V	-		10	μА
		V _{DS} = 720 V, T _C = 125°C	-		100	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-		100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	-		-100	nA
On Charact	eristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3.0 A		1.93	2.3	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 3.0 A	-	5.5		S
Dynamic Ch	haracteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,		1360	1770	pF
C _{oss}	Output Capacitance	f = 1.0 MHz	-	110	145	pF
C _{rss}	Reverse Transfer Capacitance		-	11	15	pF
Switching C	Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 6.0A,		35	80	ns
t _r	Turn-On Rise Time	R_G = 25 Ω (Note 4)	-	90	190	ns
t _{d(off)}	Turn-Off Delay Time			55	120	ns
t _f	Turn-Off Fall Time			60	130	ns
Qg	Total Gate Charge	$V_{DS} = 720 \text{ V}, I_D = 6.0\text{A}, \ V_{GS} = 10 \text{ V}$	-	30	40	nC
Q _{gs}	Gate-Source Charge		-	9.0		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		12		nC
Drain-Source	ce Diode Characteristics and Maximum Ratings				*	
I _S	Maximum Continuous Drain-Source Diode Forward Current				6.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-		24	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 6.0 A	-		1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 6.0 A,	-	630		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		6.9		μС

^{1.} Repetitive rating: pulse-width limited by maximum junction temperature.

^{2.} L = 34 mH, I $_{AS}$ = 6 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 $\Omega,$ starting T $_{J}$ = 25 $^{\circ}C.$

 $^{3.}I_{SD} \leq 6 \text{ A, di/dt} \leq 200 \text{ A/}\mu\text{s, V}_{DD} \leq \text{BV}_{DSS}\text{, starting T}_{J} = 25^{\circ}\text{C}.$

^{4.} Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

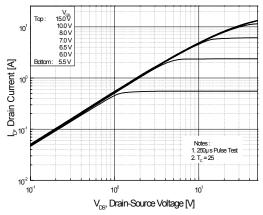


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

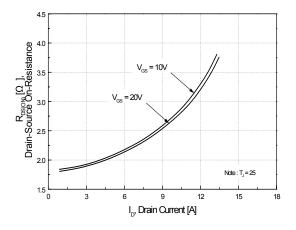


Figure 5. Capacitance Characteristics

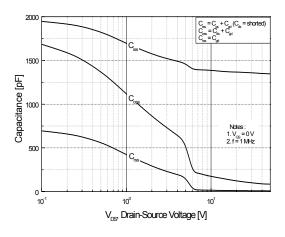


Figure 2. Transfer Characteristics

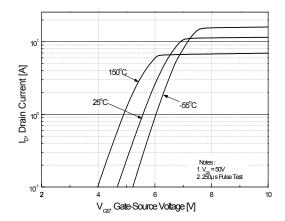


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

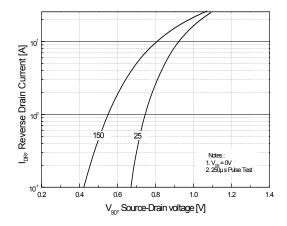
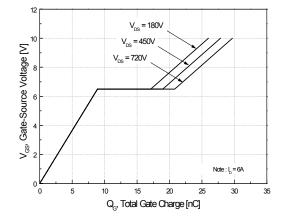


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

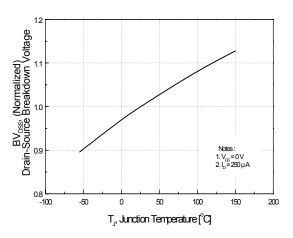


Figure 9. Maximum Safe Operating Area

Figure 8. On-Resistance Variation vs. Temperature

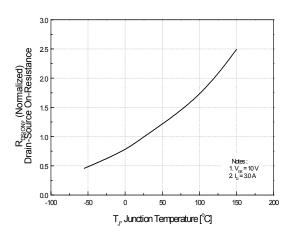


Figure 10. Maximum Drain Current vs. Case Temperature

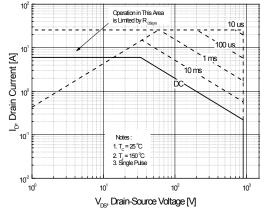
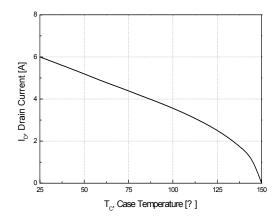
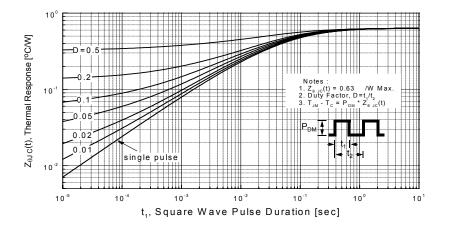


Figure 11. Transient Thermal Response Curve





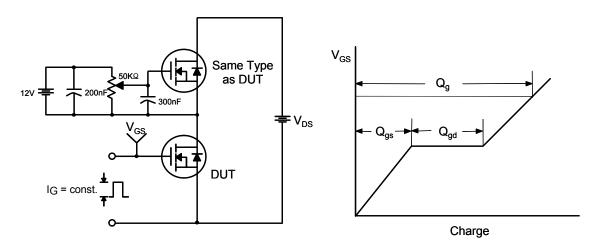


Figure 12. Gate Charge Test Circuit & Waveform

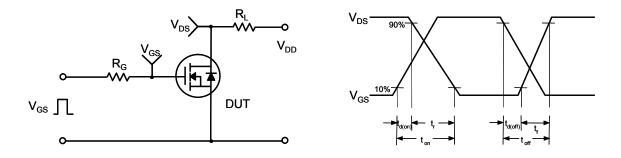


Figure 13. Resistive Switching Test Circuit & Waveforms

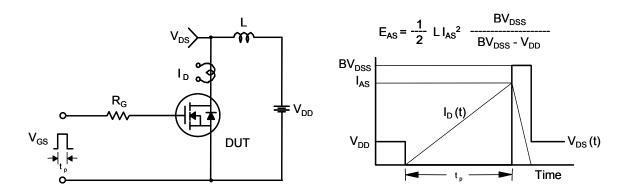
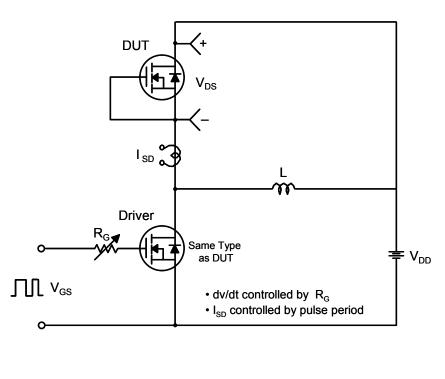


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



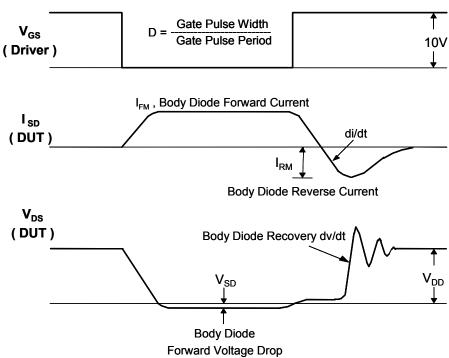
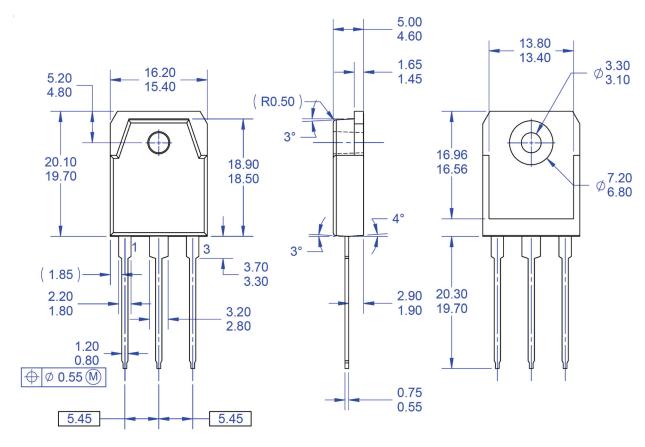
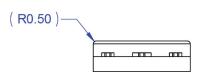


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
 E) DRAWING FILE NAME: TO3PN03AREV1.

Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

Package drawings are provided as a service to customers considering ON Semiconductor components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a ON Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of ON Semiconductor's worldwide terms and conditions, specifically the warranty therein, which covers ON Semiconductor products.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative